

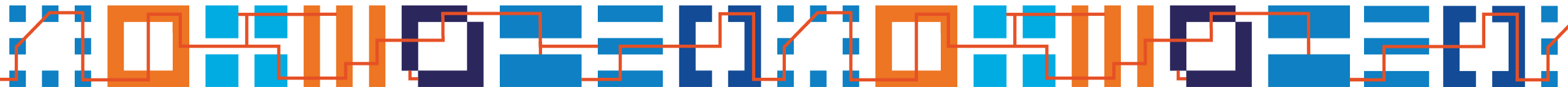


Educating the next generation of packaging experts

Joop Bruines

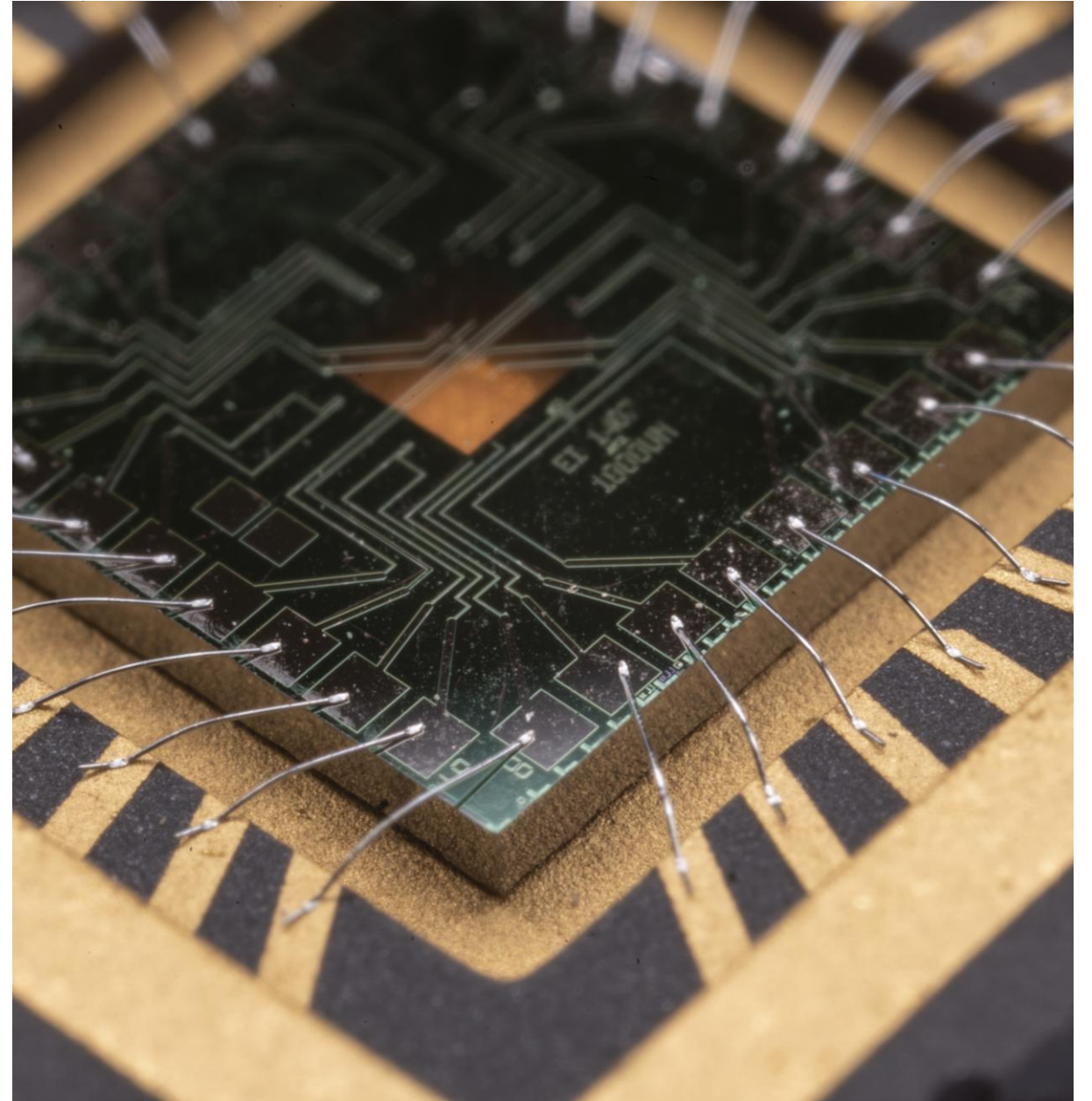


Chip Integration
Technology Center



CITC's educational ambition

- Securing the future of the semiconductor industry in Europe
- By... contributing to the training and skills of people that align with industry needs
- People who are in high demand – now and in the future



Providing access to education



Semiconductor Packaging

- For BSc candidates and industry and academic professionals
- Theory and practice



Supervise students

- Internships
- Graduation projects
- PDEng and PhD students



Enthuse the young

- Primary and secondary school
- Guest lectures
- One-day internships

Semiconductor Packaging University Program

- Initiative of CITC, NXP, Nexperia and Ampleon
- Developed together with HAN University of Applied Sciences, TNO and TU Delft
- Provides a connection between education and industry
- Training in all relevant aspects of chip packaging and supporting disciplines



TAKE A DIVE INTO THE DEEP...

... and discover the world of semiconductor packaging

Want to broaden your horizons in semiconductor assembly and packaging?

Follow the unique CITC/HAN differentiation minor and distinguish yourself from your fellow students for a career in the semiconductor industry.

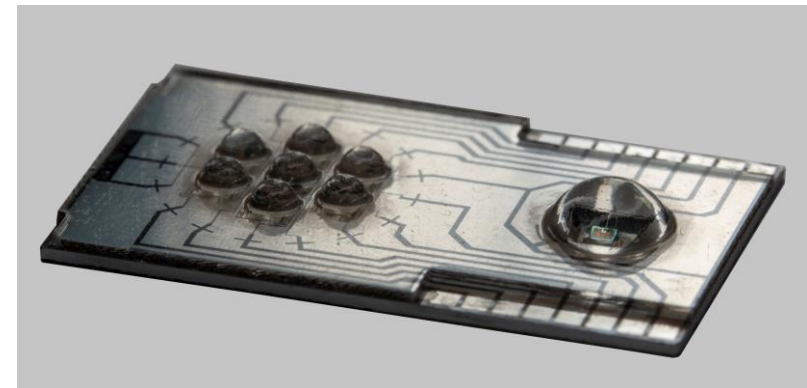
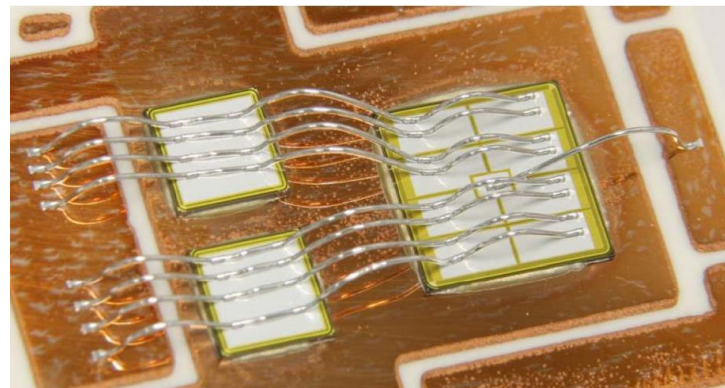
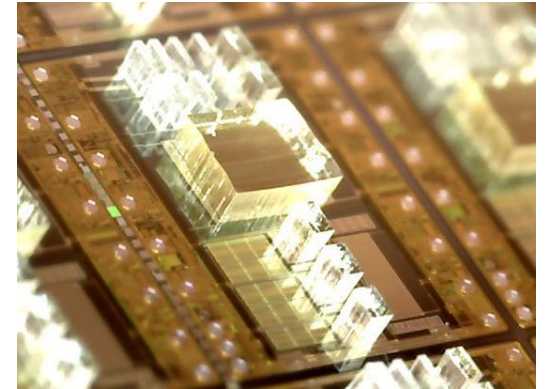
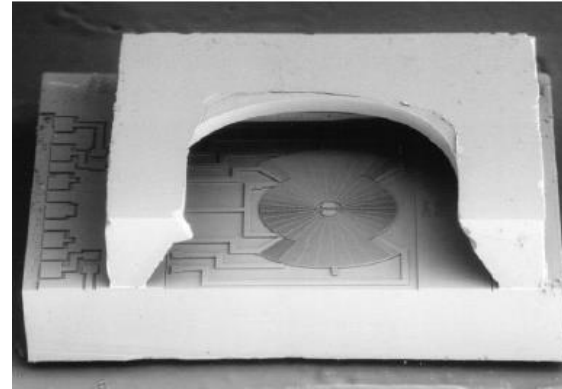
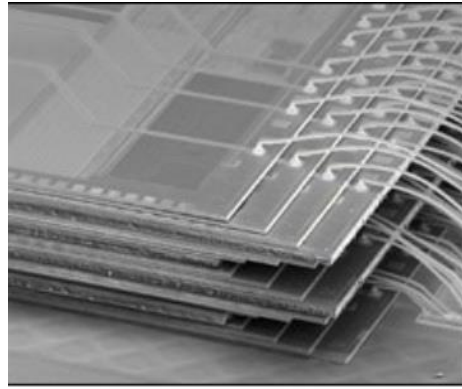
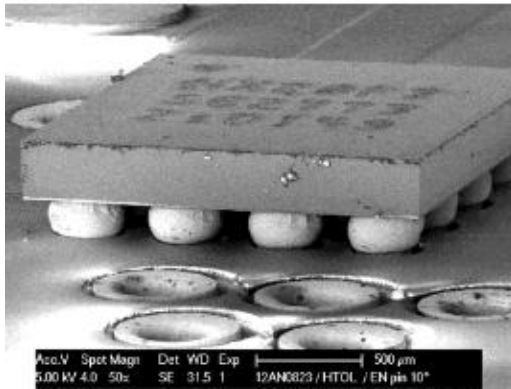
[More info >>](#)



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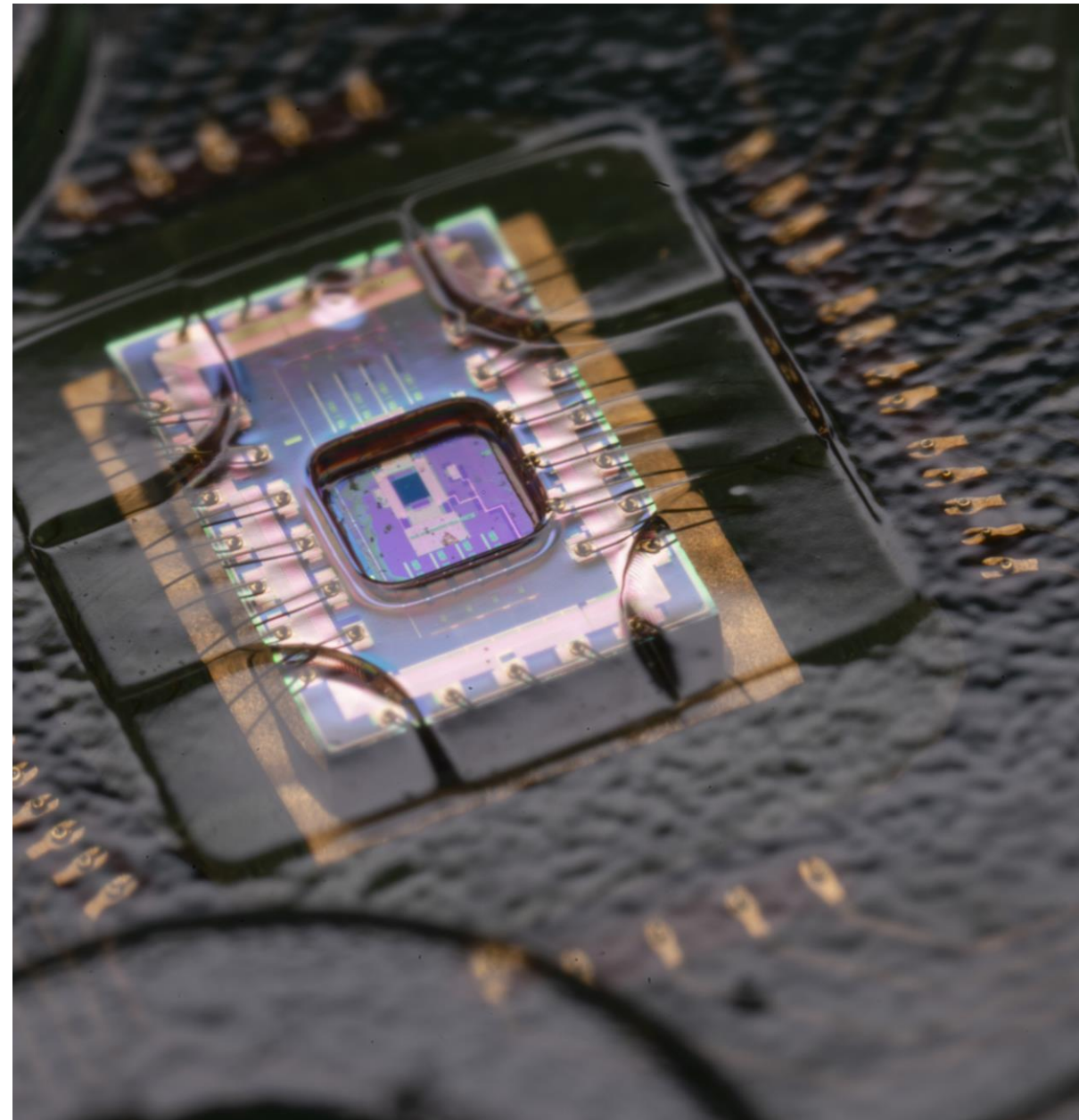


Integration and packaging challenging?



Unique, industry-driven program

- Learn from the experts
 - Lecturers are industry experts with years of practical experience
 - Student visits to leading semiconductor manufacturing and equipment companies included
- Multidisciplinary class
 - Group consists of both bachelor students and professionals from industry and academia
 - Various educational backgrounds
- Valuable skills
 - Students learn to collaborate in a cross-functional environment
 - Work with people from different cultures and in different situations



Program content

Course for industry and academic professionals

- Seven-day course – 7 consecutive Mondays
- Optional: week of practical work
 - Selected number of participants only
 - Under supervision of CITC
 - Specific packaging challenge

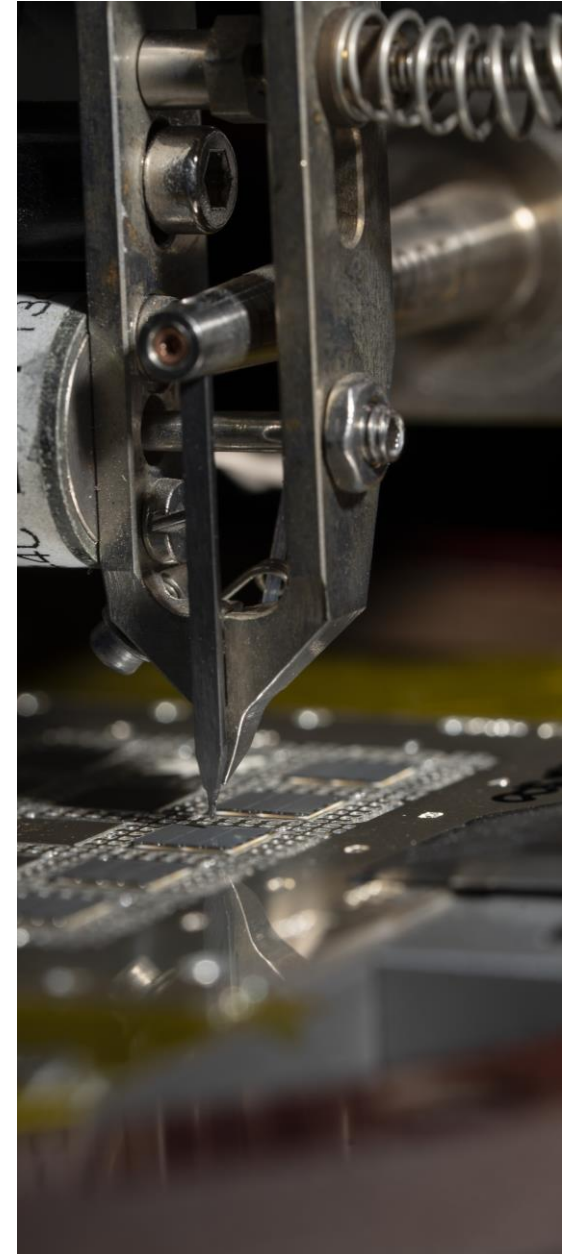
Minor for bachelor students*

- Same seven-day course lectures as professionals
- Industry orientation program with
 - Additional and supplementary lectures
 - Weekly individual assignments
 - Workshops
 - Company visits
- Term-1 closed by written and oral exam
- Practical team assignments during term-2
 - At CITC and industrial partners
- Additionally, self-studies on selected topics

* *Electrical engineering, mechanical engineering, mechatronics, automotive, chemistry, technical business administration*

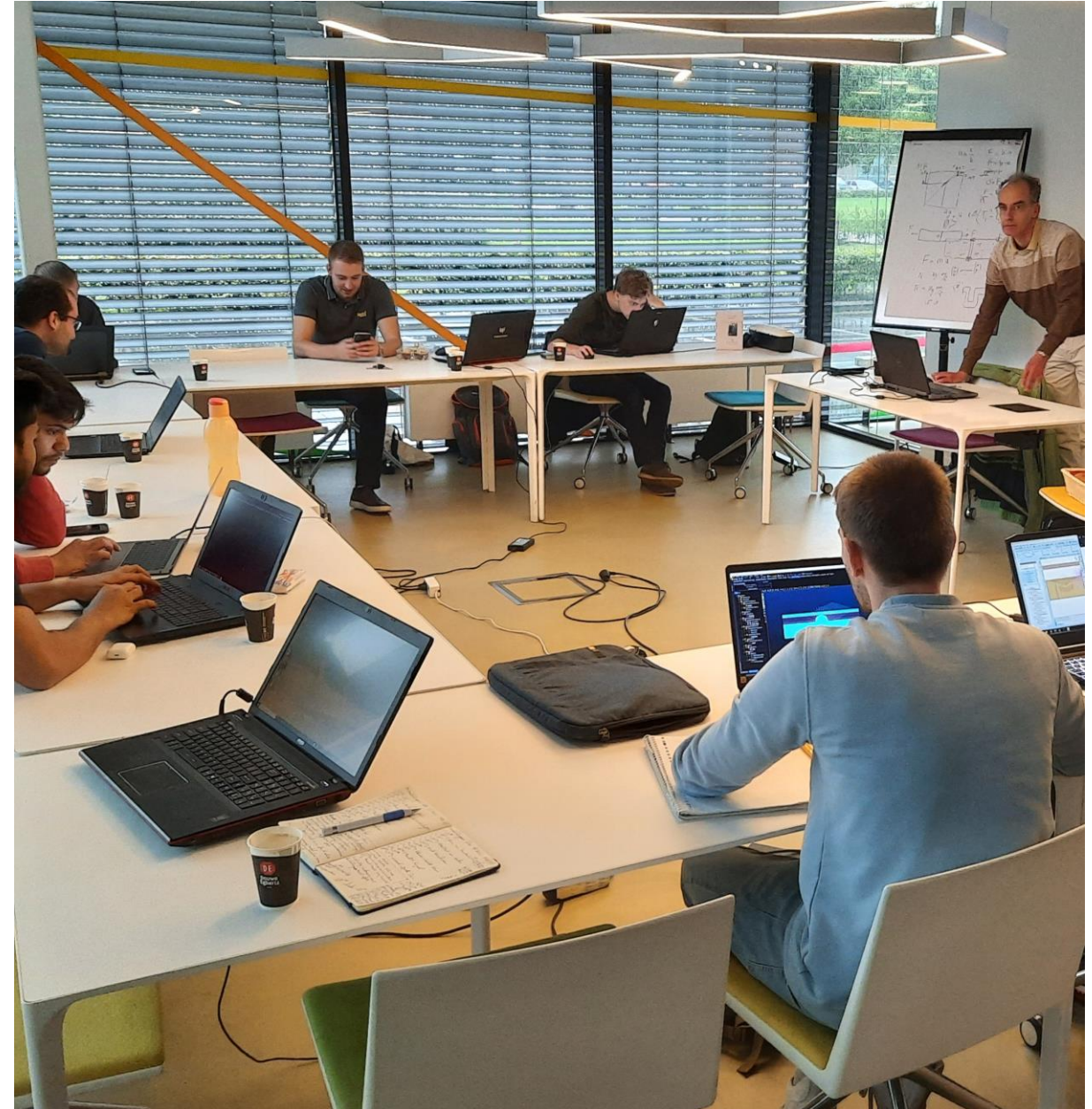
Learning objectives

- Understand the semiconductor world
- Communicate with the IC front-end, assembly and packaging experts
- Gain insight into the cross-functional challenges in IC packaging
- Work in a systematic way, according to protocols and standards
- Design and implement prototypes to customer specification
- Analyse electrical test and reliability data



Program minor term-1

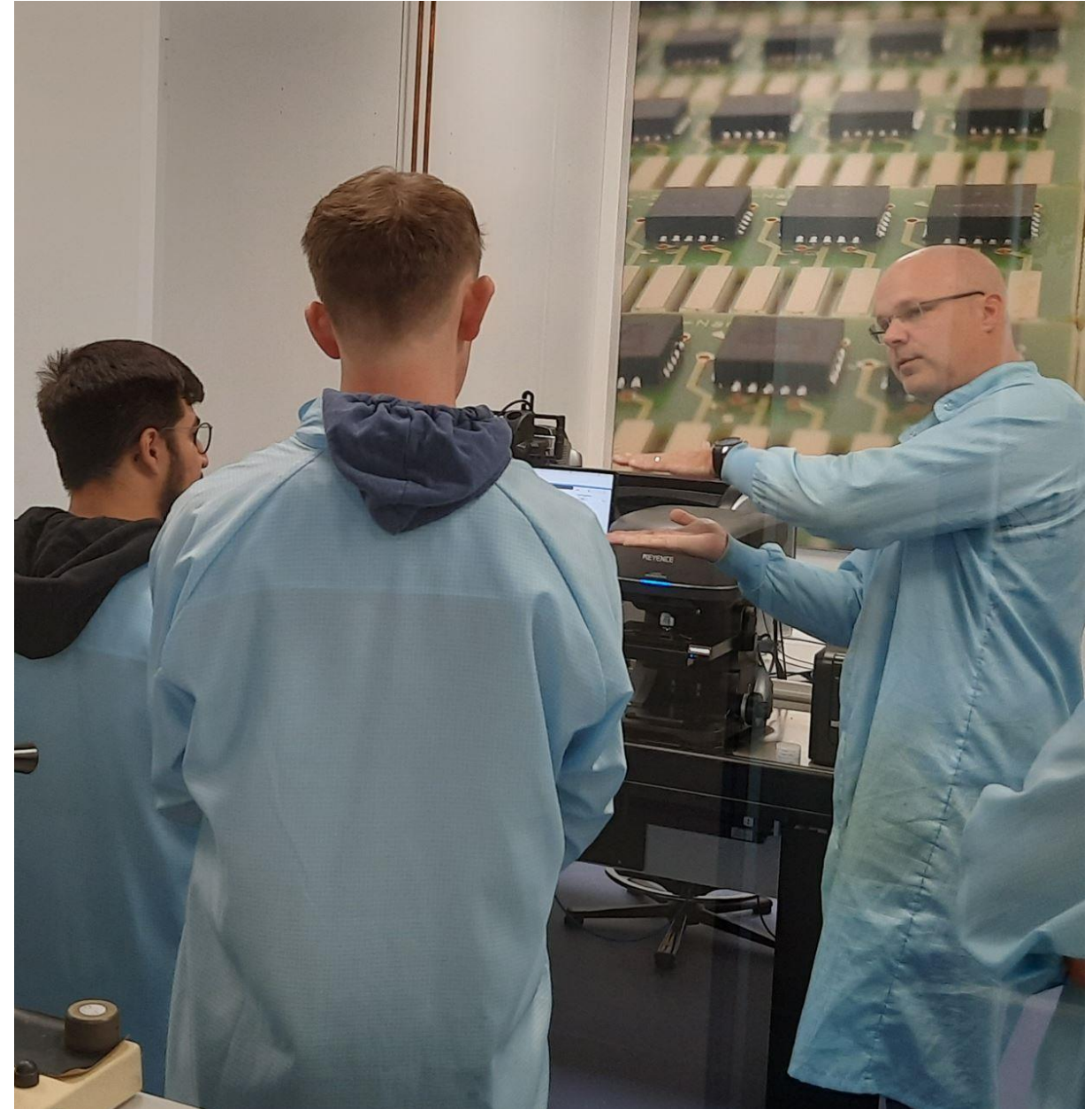
- Get acquainted with the industry
 - Gain general insight into the industry
 - Visit companies
- Learn about chips and their packaging
 - Microelectronics and their packaging
 - Integrated photonics and their packaging
 - Application requirements and trends
 - Simulation and advanced materials
 - Reliability, quality and testing



Program minor term 2

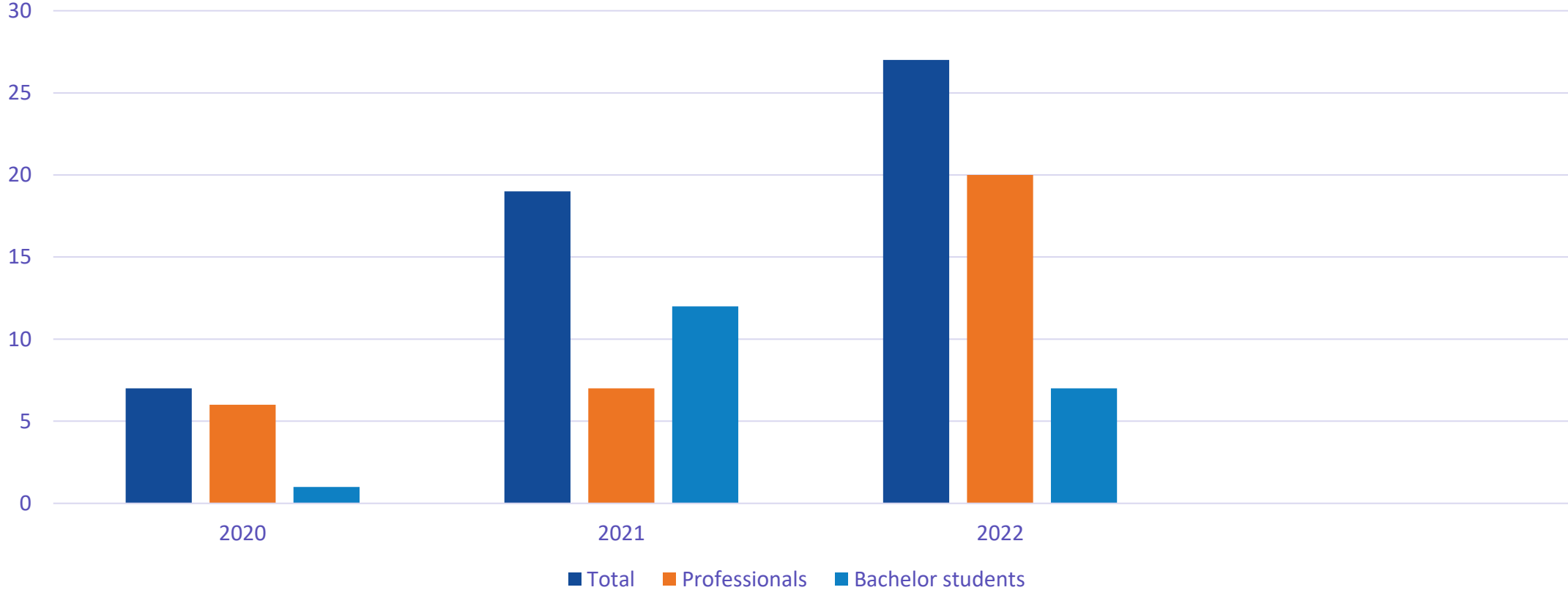
- Tackle a challenging problem
 - Work in a team
 - Create a prototype to demonstrate concept and feasibility
 - Practical work at industrial partner and CITC

- Self-study specialization in two disciplines:
 - Thermo-mechanical simulation
 - Advanced packaging materials
 - Quality control and reliability
 - Industrialization and equipment
 - Testing and data analysis
 - Integrated optics
 - ...



People trained in previous editions

Participants



Next edition

- ... begins on Monday August 28
- Already registered:
 - 13 bachelor students (3 from RWTH)
 - 16 academic professionals
 - 4 industry professionals
- Registration ends on July 3rd - you are welcome to join!



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Thank you for your attention!



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